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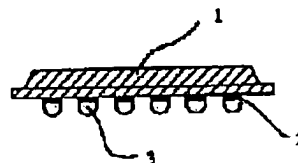
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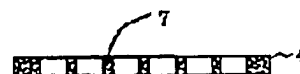
INT.CL. : H05K 1/18 H05K 3/34

TITLE : METHOD FOR MOUNTING LSI
PACKAGE HAVING METALLIC BUMP

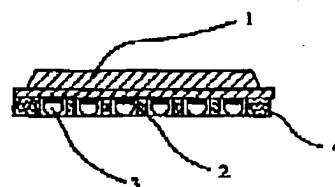
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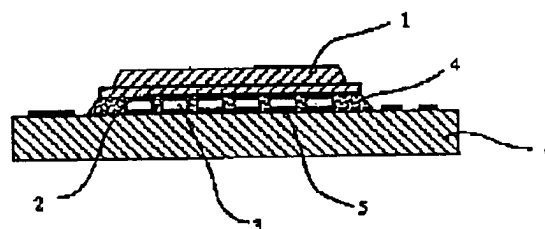
(b)



(c)



(d)



ABSTRACT : PURPOSE: To provide a method by which the reliability of the connection can be improved between an LSI package having metallic bumps and a printed wiring board after the package is mounted on the board.

CONSTITUTION: After a film-like sheet 4 composed of an organic resin having a melting point and coefficient of thermal expansion nearly equal to those of metallic bumps 3 and holes in corresponding to the positions and shapes of the corresponding metallic bumps 3 is put on the bump surface of an LSI package 1 having the metallic bumps 3 and the package 1 is mounted on a wiring board 6, the package 1 is connected to the wiring board 6 in a reflow furnace.

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